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MMBT3906

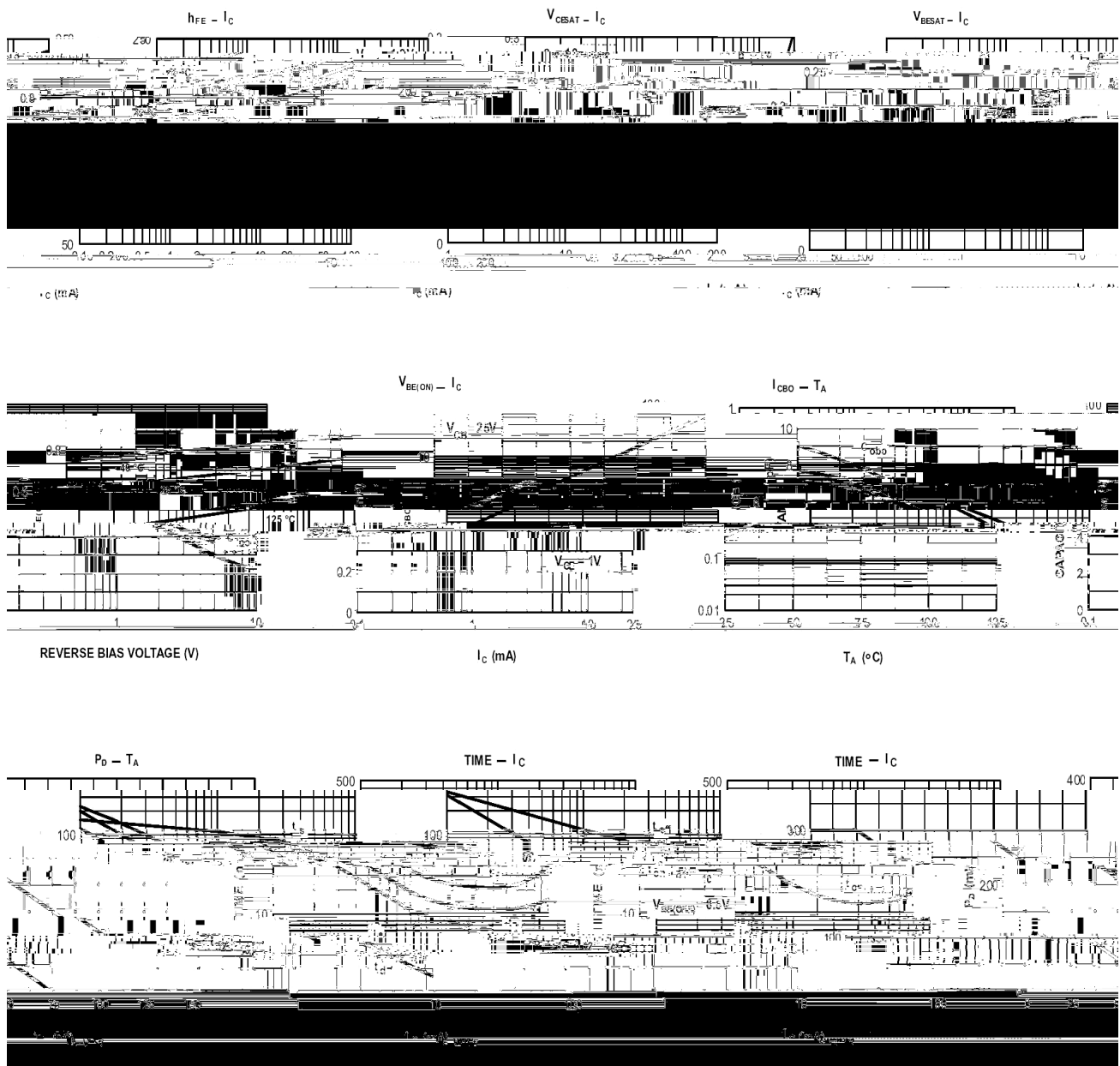


i j Parameter	k l Symbol	j m Rating	n o Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-200	mA
Collector Power Dissipation	P_C	300	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

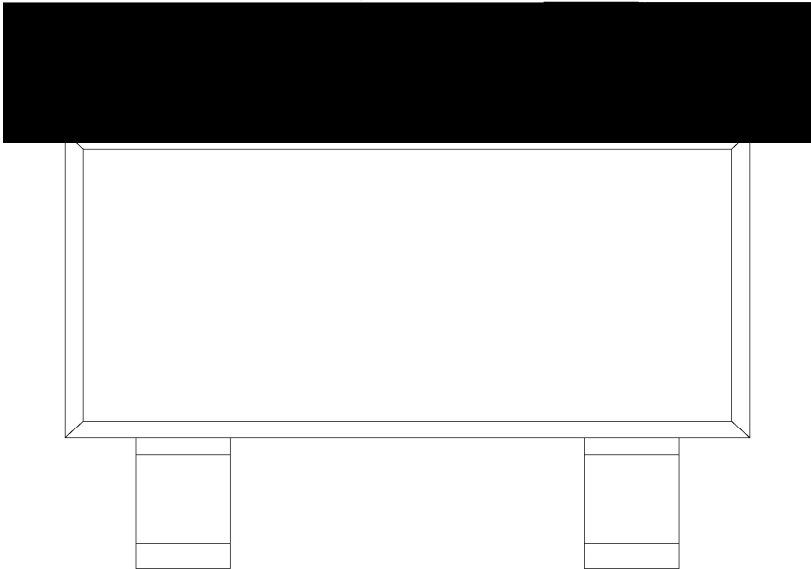
i j Parameter	k l Symbol	p q r s Test Conditions	t u m v w m Min T
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i j

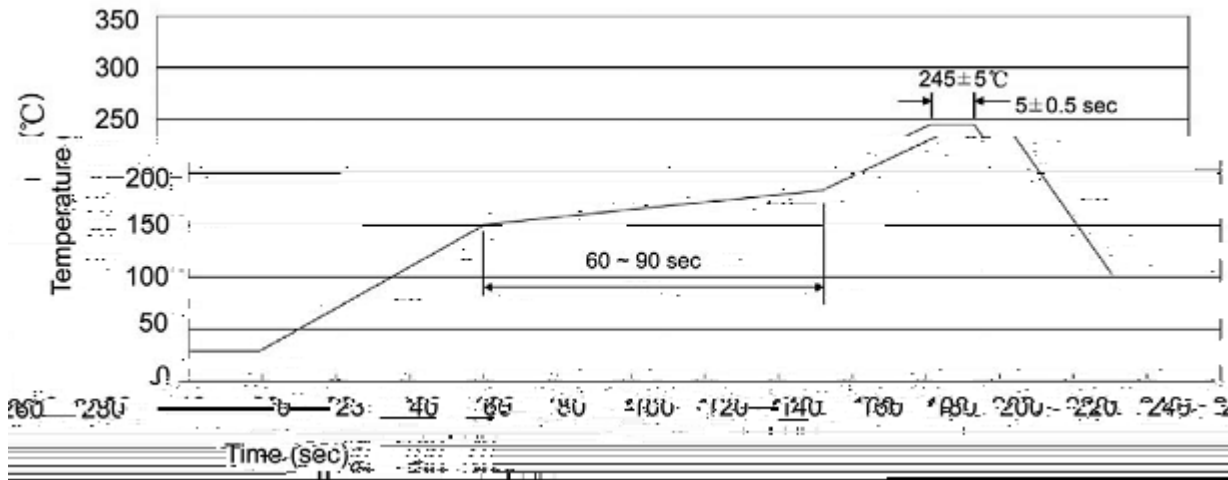
/ Electrical Characteristic Curve



The figure consists of two parts. The top part is a cross-sectional schematic of a channel. It shows a central jet of width $2b$ and height h entering from the left. The channel has a total width $2a$ and height $2h$. The bottom part is a plan view of the channel. It shows a central jet of width $2b$ and height h entering from the left. The channel has a total width $2a$ and height $2h$. The flow rates are labeled as Q_1 for the central jet and Q_2 for the side jets. The dimensions are labeled as a , b , and h . The flow rates are also labeled as $Q_1 = 0.45$, $Q_2 = 0.67$, and $Q_3 = 0.85$. The dimensions are also labeled as $a = 0.5$, $b = 0.25$, and $h = 0.1$.



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|---|--------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. | |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5°C	Time:10±1 sec
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/ Packaging SPEC.

/ REEL

Package Type	Units "	# \$	Dimension "	% &	(unit ' mm ³)
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